

**PATENT ASSIGNMENT**

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Shouji Shiotsuki	01/18/2006
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Sakata Seed Corporation
<b>Street Address:</b>	2-7-1 Nakamachidai, Tsuzuki-ku
<b>City:</b>	Yokohama
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	224
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11337402
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(303)799-6898
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	303-799-6444
<b>Email:</b>	kschuett@jondlelaw.com
<b>Correspondent Name:</b>	Jondle & Associates P.C.
<b>Address Line 1:</b>	858 Happy Canyon Road
<b>Address Line 2:</b>	Suite 230
<b>Address Line 4:</b>	Castle Rock, COLORADO 80108
<b>ATTORNEY DOCKET NUMBER:</b>	1236-099PP
<b>NAME OF SUBMITTER:</b>	Kenyon L. Schuett
<b>Total Attachments: 1</b> source=assignment 1236-099PP#page1.tif	

**OP \$40.00 11337402**

**ASSIGNMENT**

WHEREAS, I, SHOUJI SHIOTSUKI, a citizen of Japan, residing at Endo 17, Nakai-machi, Ashigara Kami-gun, Kanagawa, Japan 259-0141, am the inventor of an invention in PENTAS PLANT NAMED 'NAKPEN004' for which an application for Letters Patent is being filed with the United States Patent and Trademark Office; and

WHEREAS, SAKATA SEED CORPORATION, a Japanese corporation with a place of business at 2-7-1 Nakamachidai, Tsuzuki-ku, Yokohama, Japan 224 is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said SHOUJI SHIOTSUKI have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said SAKATA SEED CORPORATION, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention and the said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said invention in any country or countries foreign to the United States, and all Letters Patent which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof and all rights of priority in any such country or countries based upon the filing of the said application for Letters Patent of the United States which are created by any law, treaty or international convention; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said SAKATA SEED CORPORATION, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said SAKATA SEED CORPORATION, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said SAKATA SEED CORPORATION, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal.

18. January, 2006

S. Shiotsuki  
SHOUJI SHIOTSUKI